

LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC1060ACN#PBF

(Engineering Calculation)

FDP

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TOTAL MASS (g): 1.36193

COMPONENT MATERIAL	VENDOR/INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL Pkg.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000230	1000000	2840.12696289		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.386100	975000	283494.65625		
		Iron (Fe)	7439-89-6	0.009504	24000	6978.32958984		
		Phosphorus (P)	7723-14-0	0.000119	300	87.3759689331		
		Zinc (Zn)	7440-66-6	0.000277	700	203.387786865		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-99-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		<b>Lead Frame Total:</b>				<b>0.396000</b>	<b>1000000</b>	<b>290743.75</b>
		Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0
Exter. Plating Sn	7440-31-5			0.011039	1000000	22790.0800781		
<b>External Plating Total:</b>						<b>0.011039</b>	<b>1000000</b>	<b>22790.0800781</b>
Inter. Plating Ni	7440-02-0			0.000000	0	0		
Inter. Plating Ag	7440-22-4			0.003168	1000000	2326.10996328		
<b>Internal Plating Total:</b>						<b>0.003168</b>	<b>1000000</b>	<b>2326.10996328</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001335	750000	980.226118359		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000445	250000	326.74295947		
		<b>Die Attach Total:</b>				<b>0.001780</b>	<b>1000000</b>	<b>1306.96838379</b>
		Encapsulation	MULTIAROMATIC RESIN BzSb FREE	Resin (EP)	0.124740	135000	91590.578125	
Bromine (Br)	40039-03-8			0.000000	0	0		
Silica (SiO2)	60676-86-0			0.794640	860000	583465.9375		
Antimony Trioxide (Sb2O3)	1309-64-4			0.000000	0	0		
Metal Hydroxide				0.000000	0	0		
Carbon Black (C)	1333-86-4			0.004620	5000	3392.2434082		
<b>Encapsulation Total:</b>						<b>0.924000</b>	<b>1000000</b>	<b>67848.75</b>
Bond Wire Estimated	AFW/TANAKA/Kn	Gold (Au)	7440-57-5	0.000714	1000000	524.255859375		

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